IPC ASSOCIATION CONNEC ELECTRONICS INDUST	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier Info	rmation													
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
ısemi											2025-09-12			
Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			P	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA NA				Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Veight*	UOM	Unit Type
	2SA2125-TD-E BIP PN		BIP PNP 3A 50V	SIP PNP 3A 50V		2025-09-12 CNG		NG	5	1.48	mg	Each		
	ng Process Informa		arminal Daga	Alloy	STD-020 MSL	Dating	Dook Proof	ass Pody To	mmoratur	May Time at Peak	Tomporatu	ura Numb	per of Reflow Cyo	alac
			Terminal Base Alloy J-STI CU Alloy 1		31D-020 MSL	Kaung		Peak Process Body Tempera 260 C					er of Reflow Cyc	nes
	IIS DI	I C	O Anoy	1			200		IC .	] 30	second	15   3		
omments	n time at neak tamperat	uno dunina sol	doring is 10.	20 seconds										
	n time at peak temperat ation regarding materia													

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cornect to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to su										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.31	mg	Supplier	Silicon (Si)	7440-21-3		0.31	mg
Die Attach Solder	0.15	mg	Supplier	Silver (Ag)	7440-22-4		0.0038	mg
			A	Lead (Pb)	7439-92-1	7a	0.1388	mg
			Supplier	Tin (Sn)	7440-31-5		0.0075	mg
Lead Frame	22.4	mg	Supplier	Silver (Ag)	7440-22-4		0.0986	mg
			Supplier	Tin (Sn)	7440-31-5		0.0314	mg
			Supplier	Copper (Cu)	7440-50-8		22.2701	mg
Mold Compound-Black	27.66	mg		Brominated epoxy resin	proprietary data		0.3872	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		1.2447	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2489	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2766	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.745	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		4.7022	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0553	mg
Plating	0.77	mg	В	Bismuth (Bi)	7440-69-9		0.0046	mg
			Supplier	Tin (Sn)	7440-31-5		0.7654	mg
Wire Bond - Au	0.19	mg	Supplier	Gold (Au)	7440-57-5		0.19	mg